BC237B

Amplifier Transistors

NPN Silicon

Features

- Pb−Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V_{CEO}	45	Vdc
Collector–Emitter Voltage	V_{CES}	50	Vdc
Collector–Emitter Voltage	V_{EBO}	6.0	Vdc
Collector Current – Continuous	I_C	100	mAdc
Total Power Dissipation @ $T_A = 25°C$ Derate above $T_A = 25°C$	P_D	350 2.8	mW mW/°C
Total Power Dissipation @ $T_A = 25°C$ Derate above $T_A = 25°C$	P_D	1.0 8.0	W mW/°C
Operating and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	357	°C/W
Thermal Resistance, Junction–to–Case	$R_{\theta JC}$	125	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
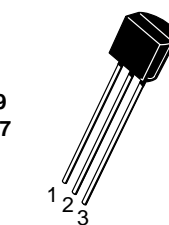
COLLECTOR
1

2
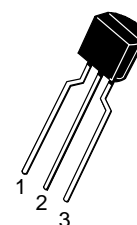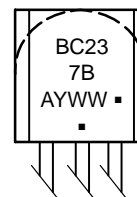BASE

3
EMITTER
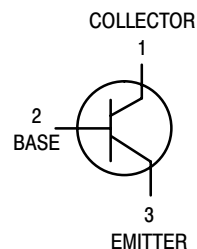
TO−92
CASE 29
STYLE 17

1
2
3
STRAIGHT LEAD
BULK PACK

1
2
3
BENT LEAD
TAPE & REEL
AMMO PACK

MARKING DIAGRAM

BC23
7B
AYWW ▪

A   = Assembly Location
Y   = Year
WW   = Work Week
▪   = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BC237B	TO−92	5000 Units / Bulk
BC237BG	TO−92 (Pb−Free)	5000 Units / Bulk
BC237BRL1G	TO−92 (Pb−Free)	2000 / Tape & Reel

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BC237B

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (I_C = 2.0 mA, I_B = 0)	$V_{(BR)CEO}$	45	–	–	V
Emitter–Base Breakdown Voltage (I_E = 100 μA, I_C = 0)	$V_{(BR)EBO}$	6.0	–	–	V
Collector Cutoff Current (V_{CE} = 50 V, V_{BE} = 0) (V_{CE} = 50 V, V_{BE} = 0) T_A = 125°C	I_{CES}	– –	0.2 0.2	15 4.0	nA μA
ON CHARACTERISTICS					
DC Current Gain (I_C = 10 μA, V_{CE} = 5.0 V) (I_C = 2.0 mA, V_{CE} = 5.0 V) (I_C = 100 mA, V_{CE} = 5.0 V)	h_{FE}	– 200 –	150 290 180	– 460 –	–
Collector–Emitter On Voltage (I_C = 10 mA, I_B = 0.5 mA) (I_C = 100 mA, I_B = 5.0 mA)	$V_{CE(sat)}$	– –	0.07 0.2	0.2 0.6	V
Base–Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA) (I_C = 100 mA, I_B = 5.0 mA)	$V_{BE(sat)}$	– –	0.6 –	0.83 1.05	V
Base–Emitter On Voltage (I_C = 100 μA, V_{CE} = 5.0 V) (I_C = 2.0 mA, V_{CE} = 5.0 V) (I_C = 100 mA, V_{CE} = 5.0 V)	$V_{BE(on)}$	– 0.55 –	0.5 0.62 0.83	– 0.7 –	V
DYNAMIC CHARACTERISTICS					
Current–Gain — Bandwidth Product (I_C = 0.5 mA, V_{CE} = 3.0 V, f = 100 MHz) (I_C = 10 mA, V_{CE} = 5.0 V, f = 100 MHz)	f_T	– 150	100 200	– –	MHz
Collector–Base Capacitance (V_{CB} = 10 V, I_C = 0, f = 1.0 MHz)	C_{obo}	–	–	4.5	pF
Emitter–Base Capacitance (V_{EB} = 0.5 V, I_C = 0, f = 1.0 MHz)	C_{ibo}	–	8.0	–	pF
Noise Figure (I_C = 0.2 mA, V_{CE} = 5.0 V, R_S = 2.0 kΩ, f = 1.0 kHz, Δf = 200 Hz)	NF	–	2.0	10	dB

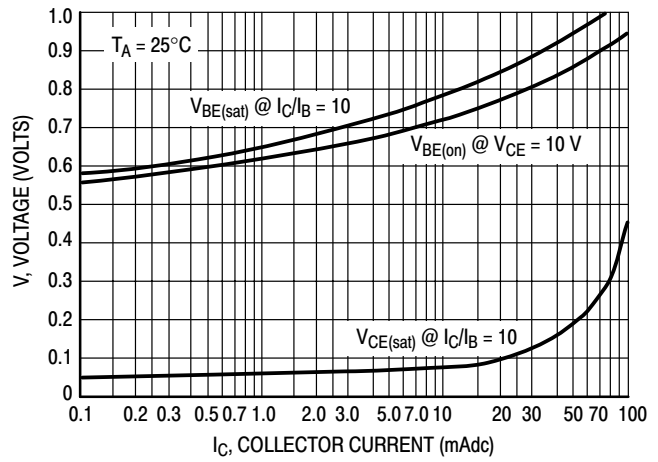# BC237B
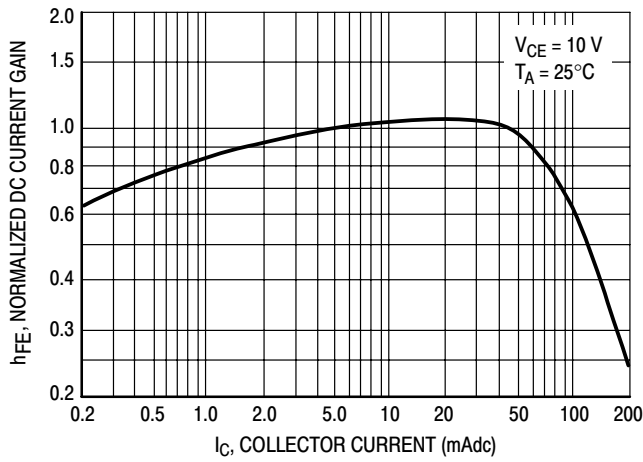
Figure 1. Normalized DC Current Gain

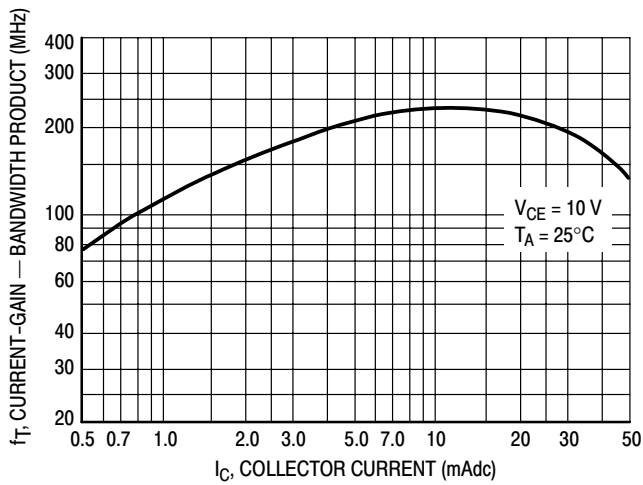Figure 2. "Saturation" and "On" Voltages

Figure 3. Current–Gain — Bandwidth Product

Figure 4. Capacitances
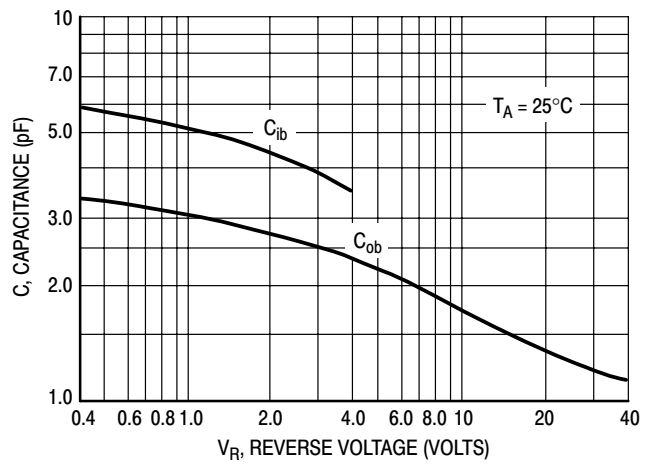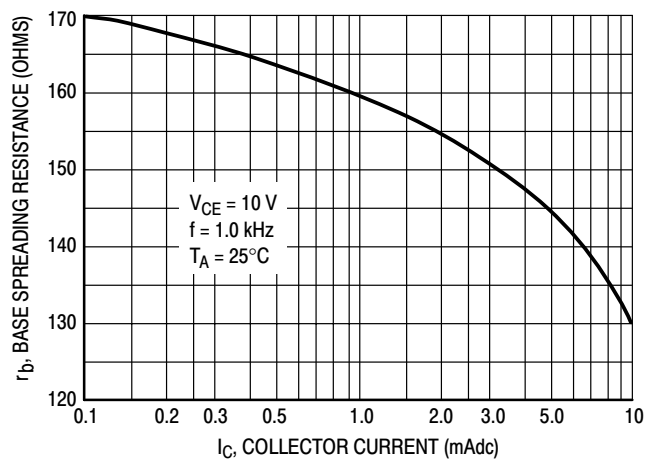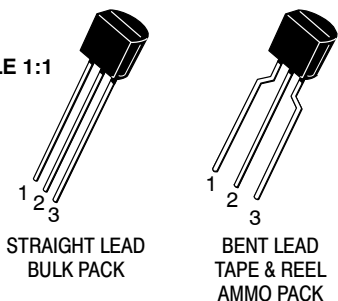

Figure 5. Base Spreading Resistance

http://onsemi.com

3

SCALE 1:1

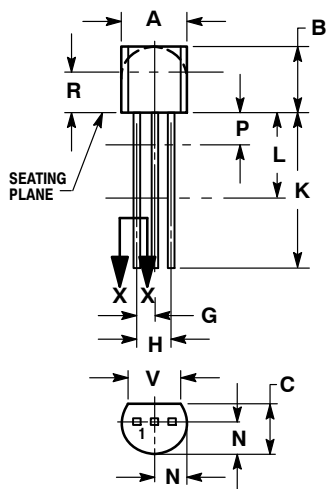STRAIGHT LEAD
BULK PACK

BENT LEAD
TAPE & REEL
AMMO PACK

1
2
3

1
2
3

TO−92 (TO−226)
CASE 29−11
ISSUE AM

DATE 09 MAR 2007

STRAIGHT LEAD
BULK PACK

SEATING
PLANE

SECTION X−X
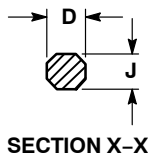
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---

BENT LEAD
TAPE & REEL
AMMO PACK

SEATING
PLANE

SECTION X−X
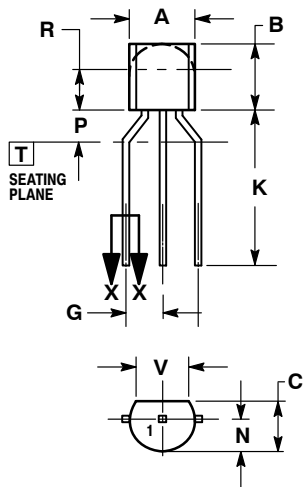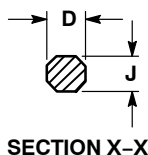
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS MIN	MILLIMETERS MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLES ON PAGE 2

DOCUMENT NUMBER:	**98ASB42022B**
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DESCRIPTION:	**TO−92 (TO−226)**

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PAGE 1 OF 3

STYLE 1:
PIN 1. EMITTER
    2. BASE
    3. COLLECTOR

STYLE 2:
PIN 1. BASE
    2. EMITTER
    3. COLLECTOR

STYLE 3:
PIN 1. ANODE
    2. ANODE
    3. CATHODE

STYLE 4:
PIN 1. CATHODE
    2. CATHODE
    3. ANODE

STYLE 5:
PIN 1. DRAIN
    2. SOURCE
    3. GATE

STYLE 6:
PIN 1. GATE
    2. SOURCE & SUBSTRATE
    3. DRAIN

STYLE 7:
PIN 1. SOURCE
    2. DRAIN
    3. GATE

STYLE 8:
PIN 1. DRAIN
    2. GATE
    3. SOURCE & SUBSTRATE

STYLE 9:
PIN 1. BASE 1
    2. EMITTER
    3. BASE 2

STYLE 10:
PIN 1. CATHODE
    2. GATE
    3. ANODE

STYLE 11:
PIN 1. ANODE
    2. CATHODE & ANODE
    3. CATHODE

STYLE 12:
PIN 1. MAIN TERMINAL 1
    2. GATE
    3. MAIN TERMINAL 2

STYLE 13:
PIN 1. ANODE 1
    2. GATE
    3. CATHODE 2

STYLE 14:
PIN 1. EMITTER
    2. COLLECTOR
    3. BASE

STYLE 15:
PIN 1. ANODE 1
    2. CATHODE
    3. ANODE 2

STYLE 16:
PIN 1. ANODE
    2. GATE
    3. CATHODE

STYLE 17:
PIN 1. COLLECTOR
    2. BASE
    3. EMITTER

STYLE 18:
PIN 1. ANODE
    2. CATHODE
    3. NOT CONNECTED

STYLE 19:
PIN 1. GATE
    2. ANODE
    3. CATHODE

STYLE 20:
PIN 1. NOT CONNECTED
    2. CATHODE
    3. ANODE

STYLE 21:
PIN 1. COLLECTOR
    2. EMITTER
    3. BASE

STYLE 22:
PIN 1. SOURCE
    2. GATE
    3. DRAIN

STYLE 23:
PIN 1. GATE
    2. SOURCE
    3. DRAIN

STYLE 24:
PIN 1. EMITTER
    2. COLLECTOR/ANODE
    3. CATHODE

STYLE 25:
PIN 1. MT 1
    2. GATE
    3. MT 2

STYLE 26:
PIN 1. V_{CC}
    2. GROUND 2
    3. OUTPUT

STYLE 27:
PIN 1. MT
    2. SUBSTRATE
    3. MT

STYLE 28:
PIN 1. CATHODE
    2. ANODE
    3. GATE

STYLE 29:
PIN 1. NOT CONNECTED
    2. ANODE
    3. CATHODE

STYLE 30:
PIN 1. DRAIN
    2. GATE
    3. SOURCE

STYLE 31:
PIN 1. GATE
    2. DRAIN
    3. SOURCE

STYLE 32:
PIN 1. BASE
    2. COLLECTOR
    3. EMITTER

STYLE 33:
PIN 1. RETURN
    2. INPUT
    3. OUTPUT

STYLE 34:
PIN 1. INPUT
    2. GROUND
    3. LOGIC

STYLE 35:
PIN 1. GATE
    2. COLLECTOR
    3. EMITTER

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TO−92 (TO−226)	PAGE 2 OF 3

ISSUE	REVISION	DATE
AM	ADDED BENT−LEAD TAPE & REEL VERSION. REQ. BY J. SUPINA.	09 MAR 2007

PUBLICATION ORDERING INFORMATION

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